

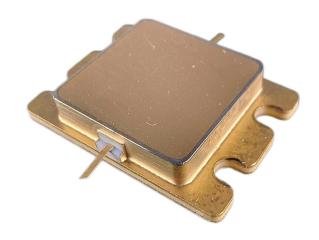
MCNI2735-P55 S-Band Internally Matched GaN Device

Key Features

■ Operating Frequency: 2.70-3.50 GHz
 ■ Saturated Output Power (Psat): ≥55 dBm

■ Power Gain(Gp): ≥11 dB

Work Efficiency (η): 50%(Type)Port Matching: Zin/Zout = 50 Ω



Product Description

The MCNI2735-P55 is an internal matching GaN device, which adopts advanced co-planar internal matching MCM and thin film circuit technology. The typical working frequency range is 2.70-3.50GHz.

This device can be used in different RF/Microwave system and subsystem. The high output power level, high efficiency and wide operating temperature range can make application very flexible.

Absolute Maximum Ratings (Tc=25°C)

Parameter	Symbol	Value	Unit	
Drain-Source Voltage	V _{DS}	60	V	
Gate-Source Voltage	V _{GS}	-5	V	
Storage Temperature	Tstg	-65 ~ +150	°C	
Channel Temperature	Tch	150	°C	

^{*}Not recommended to work under these conditions.

Microwave Electrical Characteristics

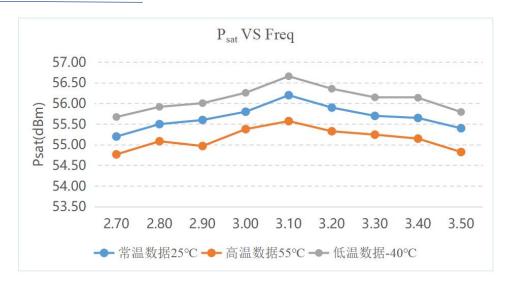
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Drain Current	dsr	VDS:50V Pulse T=1ms,Duty=20% Pin: 44dBm Freq: 2.7~3.5GHZ	-	12.6	-	Α
Saturated Output Power	P _{sat}		55	-	-	dBm
Power Gain	G _p		11	-	-	dB
Work Efficiency	η		-	50	-	%
Gain Flatness	ΔG		-0.8	-	0.8	dB



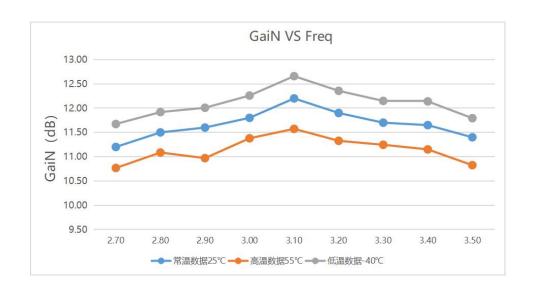


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Typical Curves





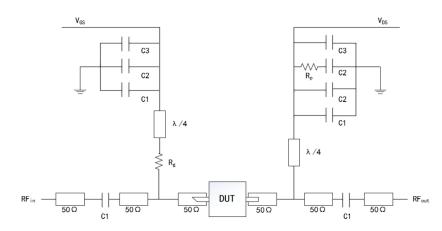




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Recommended Application Circuit



DUT: Device Under Test

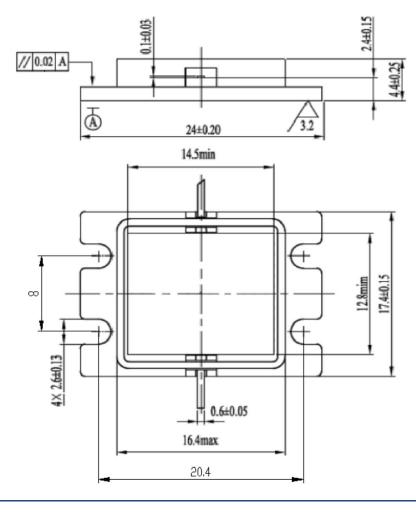
C1:8pF Rp:51 Ω C2:1000pF Rg:15 Ω

C3:100uF

ESD Level

ESD Class III	2000V
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Overall Dimensions



Using Notes:

- During transportation and storage, ensure proper drying.
- During the use and assembly of the chip, take precautions against static electricity. Wear a grounded anti-static wristband.
- When powering on, apply gate voltage first, then apply leakage voltage.